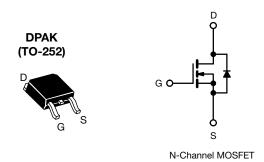


Vishay Siliconix

# **E Series Power MOSFET**



PRODUCT SUMMA	RY	
V <sub>DS</sub> (V) at T <sub>J</sub> max.	650	)
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	V <sub>GS</sub> = 10 V	0.320
Q <sub>g</sub> max. (nC)	52	
Q <sub>gs</sub> (nC)	6	
Q <sub>gd</sub> (nC)	13	
Configuration	Sing	le

#### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>a</sub>)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>



### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	DPAK (TO-252)
Lead (Pb)-free and halogen-free	SiHD9N60E-GE3

ABSOLUTE MAXIMUM RATINGS PARAMETER			SYMBOL	LIMIT	UNIT	
100000000000000000000000000000000000000				UNIT		
Drain-source voltage		$V_{DS}$	600	V		
Gate-source voltage			$V_{GS}$	± 30	V	
Continuous drain current (T <sub>.I</sub> = 150 °C)	V <sub>GS</sub> at 10 V	$T_C = 25 \degree C$ $T_C = 100 \degree C$	L	9		
Continuous drain current (1) = 130 C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C	I <sub>D</sub>	6	Α	
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	22		
Linear derating factor				0.63	W/°C	
Single pulse avalanche energy b		E <sub>AS</sub>	111	mJ		
Maximum power dissipation			P <sub>D</sub>	78	W	
Operating junction and storage temperature rai	nge		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-source voltage slope	T <sub>J</sub> =	T <sub>J</sub> = 125 °C		70	1//	
Reverse diode dV/dt <sup>d</sup>	liode dV/dt d 40		V/ns			
Soldering recommendations (peak temperature) c For 10 s			300	°C		

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $V_{DD} = 140 \text{ V}$ , starting  $T_J = 25 \,^{\circ}\text{C}$ ,  $L = 28.2 \,\text{mH}$ ,  $R_q = 25 \,\Omega$ ,  $I_{AS} = 2.8 \,\text{A}$ .
- c. 1.6 mm from case.
- d.  $I_{SD} \le I_D$ , dI/dt = 100 A/ $\mu$ s, starting  $T_J = 25$  °C.



# Vishay Siliconix

THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62	°C/W
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	1.6	G/ VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		•				•	
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.71	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.5	-	4.5	V
		$V_{GS} = \pm 20 \text{ V}$		1	-	± 100	nA
Gate-source leakage	$I_{GSS}$		$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
<del></del>		V <sub>DS</sub> =	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V		-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 \	/, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	$I_D = 4.5 A$	-	0.320	0.368	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub>	V <sub>DS</sub> = 30 V, I <sub>D</sub> = 4.5 A		2.4	-	S
Dynamic					•		
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ f = 1  MHz		-	778	-	pF
Output capacitance	C <sub>oss</sub>			-	48	-	
Reverse transfer capacitance	C <sub>rss</sub>			-	4	-	
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>	V 0VV 400VV 0V		-	29	-	
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>	V <sub>DS</sub> = 0 \	$V_{DS} = 0 \text{ V to } 480 \text{ V}, V_{GS} = 0 \text{ V}$		138	-	
Total gate charge	Qg				26	52	
Gate-source charge	$Q_{gs}$	V <sub>GS</sub> = 10 V	$I_D = 4.5 A$ , $V_{DS} = 480 V$	-	6	-	nC
Gate-drain charge	Q <sub>gd</sub>			-	13	-	
Turn-on delay time	t <sub>d(on)</sub>			-	14	28	
Rise time	t <sub>r</sub>		V <sub>DD</sub> = 480 V, I <sub>D</sub> = 4.5 A,		13	26	
Turn-off delay time	t <sub>d(off)</sub>	V <sub>GS</sub> =	= 10 V, $R_g = 9.1 \Omega$	-	31	62	ns
Fall time	t <sub>f</sub>			-	12	24	
Gate input resistance	$R_g$	f = 1 MHz, open drain		0.4	1.2	2.4	Ω
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	9	
Pulsed diode forward current	I <sub>SM</sub>			-	-	22	A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 4.5 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> = 4.5 A, dl/dt = 100 A/μs, V <sub>R</sub> = 25 V		-	207	414	ns
Reverse recovery charge	Q <sub>rr</sub>			-	2.2	4.4	μC
Reverse recovery current	I <sub>RRM</sub>			_	20	_	A

#### Notes

a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ . b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

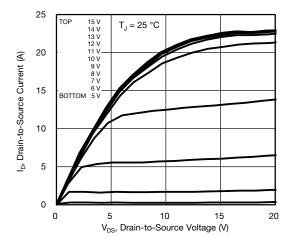


Fig. 1 - Typical Output Characteristics

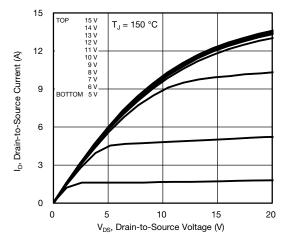


Fig. 2 - Typical Output Characteristics

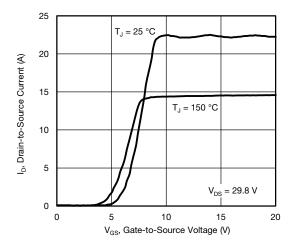


Fig. 3 - Typical Transfer Characteristics

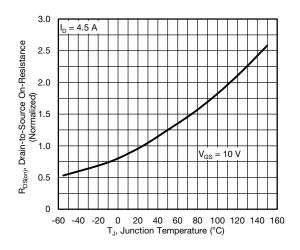


Fig. 4 - Normalized On-Resistance vs. Temperature

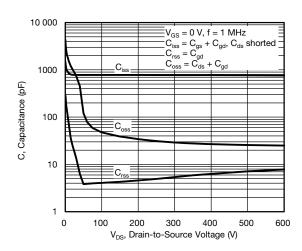


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

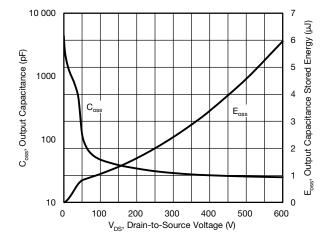


Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$ 



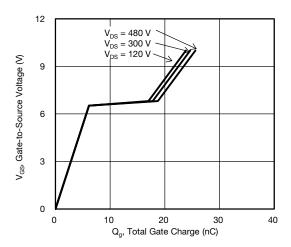


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

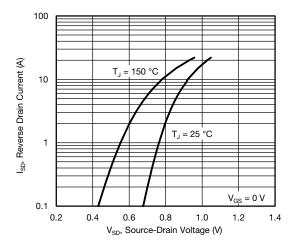


Fig. 8 - Typical Source-Drain Diode Forward Voltage

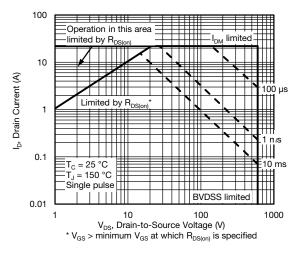


Fig. 9 - Maximum Safe Operating Area

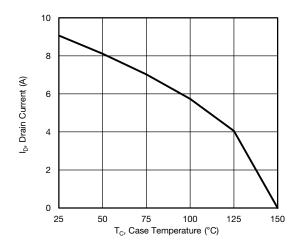


Fig. 10 - Maximum Drain Current vs. Case Temperature

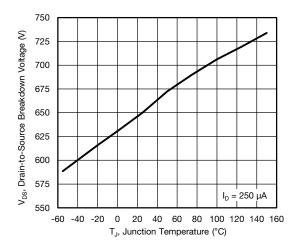


Fig. 11 - Temperature vs. Drain-to-Source Voltage



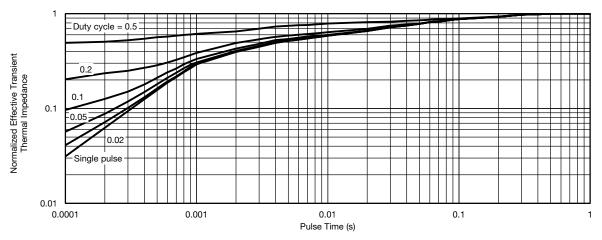


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

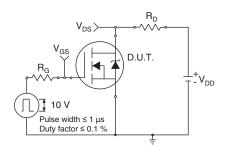


Fig. 13 - Switching Time Test Circuit

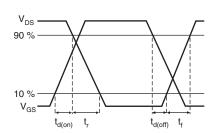


Fig. 14 - Switching Time Waveforms

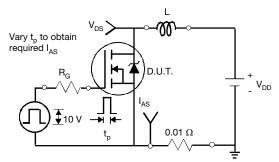


Fig. 15 - Unclamped Inductive Test Circuit

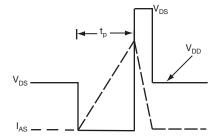


Fig. 16 - Unclamped Inductive Waveforms

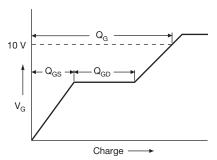


Fig. 17 - Basic Gate Charge Waveform

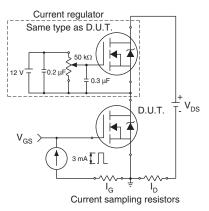
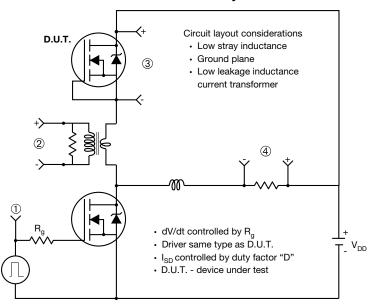


Fig. 18 - Gate Charge Test Circuit



#### Peak Diode Recovery dV/dt Test Circuit



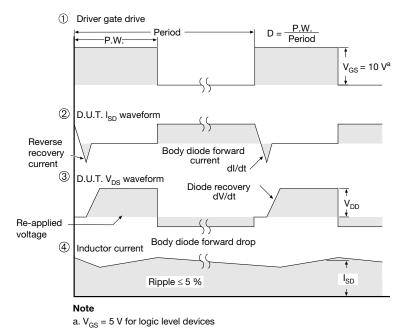
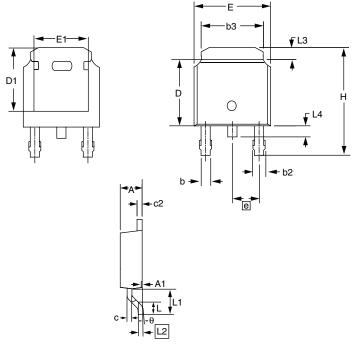


Fig. 19 - For N-Channel

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### **TO-252AA (HIGH VOLTAGE)**



	MILLI	METERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Е	6.40	6.73	0.252	0.265	
L	1.40	1.77	0.055	0.070	
L1	2.74	2.743 REF		0.108 REF	
L2	0.50	8 BSC	0.020 BSC		
L3	0.89	1.27	0.035	0.050	
L4	0.64	1.01	0.025	0.040	
D	6.00	6.22	0.236	0.245	
Н	9.40	10.40	0.370	0.409	
b	0.64	0.88	0.025	0.035	
b2	0.77	1.14	0.030	0.045	
b3	5.21	5.46	0.205	0.215	
е	2.28	2.286 BSC		0.090 BSC	
Α	2.20	2.38	0.087	0.094	
A1	0.00	0.13	0.000	0.005	
С	0.45	0.60	0.018	0.024	
c2	0.45	0.58	0.018	0.023	
D1	5.30	-	0.209	-	
E1	4.40	-	0.173	-	
θ	0'	10'	0'	10'	

ECN: S-81965-Rev. A, 15-Sep-08

DWG: 5973

#### Notes

- 1. Package body sizes exclude mold flash, protrusion or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 0.10 mm per side.
- 2. Package body sizes determined at the outermost extremes of the plastic body exclusive of mold flash, gate burrs and interlead flash, but including any mismatch between the top and bottom of the plastic body.
- 3. The package top may be smaller than the package bottom.
- 4. Dimension "b" does not include dambar protrusion. Allowable dambar protrusion shall be 0.10 mm total in excess of "b" dimension at maximum material condition. The dambar cannot be located on the lower radius of the foot.

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## **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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